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OMB No. 0651-0027 (exp. 6/30/2005)

102577280

Tab settings

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Tsai-Sheng Gau
Jaw-Jung Shin
Jan-Wen You
Burn-Jeng Lin

10-3-03

2. Name and address of receiving party(ies)

Name: Taiwan Semiconductor Manufacturing Co., Ltd.

Internal Address:

031088 U.S. PTO
10/678788



Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other

Street Address: No. 8, Li-Hsin Road 6

Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77

City: Hsin-Chu State: Zip: 300-77

Execution Date: October 2, 2003

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

10678788

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David M. O'Dell

Internal Address:

Street Address: Haynes and Boone, LLP

901 Main Street, Suite 3100

City: Dallas State: TX Zip: 75202

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number:

08-1394

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9. Signature.

David M. O'Dell

Name of Person Signing

Signature

10-3-03

Date

Total number of pages including cover sheet, attachments, and documents: 4

Mail documents to be recorded with required cover sheet information to:
Mail Stop Assignment, Commissioner of Patent, P.O. Box 1450
Alexandria, VA 22313-1450

10/09/2003 HHARZI1 00000045 10678788

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ASSIGNMENT

WHEREAS, we,

- (1) Tsai-Sheng Gau of

- (2) Jaw-Jung Shin of

- (3) Jan-Wen You of

- (4) Burn-Jeng Lin of

have invented certain improvements in

**METHOD TO IMPROVE THE CRITICAL DIMENSION UNIFORMITY OF
PATTERNED FEATURES ON WAFERS**

for which we have executed an application for Letters Patent of the United States of America, of even date herewith; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Inc., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United

States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

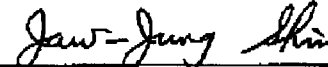
First Inventor Name: Tsai-Sheng Gau
Residence Address:

Dated: 10/1, 2003


Inventor Signature

Second Inventor Name: Jaw-Jung Shin
Residence Address:

Dated: 10/01/2003


Inventor Signature

Third Inventor Name: Jan-Wen You
Residence Address:

Dated: 10/01/2003

Jan-Wen You Jan-Wen you
Inventor Signature

Fourth Inventor Name: Burn-Jeng Lin
Residence Address:

Dated: Oct 2, 2003

Burn-Jeng Lin
Inventor Signature